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 Meets or Exceeds Requirements of ANSI TIA/EIA-422-B and ITU 	D, N, OR NS PACKAGE (TOP VIEW)			
Recommendation V.11			hver	
• 3-State, TTL-Compatible Outputs	1A [1Y [1 16 2 15	E	
Fast Transition Times	1Z [3 14	6	
High-Impedance Inputs	1,2EN [4 13] 4Z	
• Single 5-V Supply	2Z [5 12] 3,4EN	
 Power-Up and Power-Down Protection 	2Y [6 11] 3Z	
	2A [7 10] 3Y	
description/ordering information	GND [89] 3A	

The MC3487 offers four independent differential line drivers designed to meet the specifications of ANSI TIA/EIA-422-B and ITU Recommendation V.11. Each driver has a TTL-compatible input buffered to reduce current and minimize loading.

The driver outputs utilize 3-state circuitry to provide high-impedance states at any pair of differential outputs when the appropriate output enable is at a low logic level. Internal circuitry is provided to ensure the high-impedance state at the differential outputs during power-up and power-down transition times, provided the output enable is low.

The MC3487 is designed for optimum performance when used with the MC3486 quadruple line receiver. It is supplied in a 16-pin dual-in-line package and operates from a single 5-V supply.

TA	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	PDIP – N	Tube	MC3487N	MC3487N	
0°C to 70°C		Tube	MC3487D	M02407	
	SOIC – D	Tape and reel	MC3487DR	MC3487	
	SOP – NS	Tape and reel	MC3487NSR	MC3487	

ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE
(each driver)

INDUT	OUTPUT	OUT	PUTS
INPUT	ENABLE	Y	Z
Н	Н	Н	L
L	Н	L	Н
Х	L	Z	Z

H = TTL high level, L = TTL low level, X = irrelevant, Z = High impedance



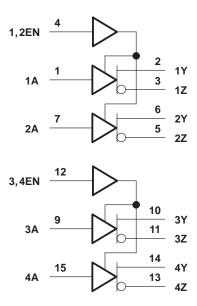
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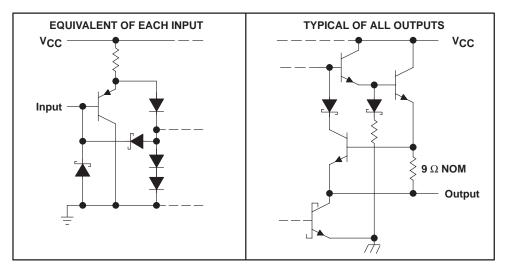


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logic diagram (positive logic)



schematics of inputs and outputs





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V _{CC} (see Note 1)	
Output voltage, V _O	
Package thermal impedance, θ_{IA} (see Notes 2 and 3):	
Package mermai impedance, OJA (see Notes 2 and 3).	
	N package
	NS package 64°C/W
Operating virtual junction temperature, T _J	150°C
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, except differential output voltage, VOD, are with respect to the network ground terminal.

- 2. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

		MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.75	5	5.25	V
VIH	High-level input voltage	2			V
VIL	Low-level input voltage			0.8	V
ТĄ	Operating free-air temperature	0		70	°C



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electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

	PARAMETER	TEST	CONDITIONS		MIN	MAX	UNIT	
VIK	Input clamp voltage	Ij = -18 mA				-1.5	V	
Vон	High-level output voltage	V _{IL} = 0.8 V,	V _{IH} = 2 V,	I _{OH} = -20 mA	2.5		V	
VOL	Low-level output voltage	V _{IL} = 0.8 V,	V _{IH} = 2 V,	I _{OL} = 48 mA		0.5	V	
Vod	Differential output voltage	R _L = 100 Ω,	See Figure 1		2			
∆ V _{OD}	Change in magnitude of differential output voltage [†]	R _L = 100 Ω,	See Figure 1			±0.4	V	
Voc	Common-mode output voltage [‡]	R _L = 100 Ω,	See Figure 1			3	V	
∆ V _{OC}	Change in magnitude of common-mode output voltage [†]	R _L = 100 Ω,	See Figure 1			±0.4	V	
	Output current with power off	N 0	VO = 6 V			100		
IO		VCC = 0	$V_{O} = -0.25 V$			-100	μA	
	I Pak Serie da se adata a da da serie d		V _O = 2.7 V			100	•	
I _{OZ} High-impedance-state output current		Output enables at 0.8 V	V _O = 0.5 V		-100		μA	
II	Input current at maximum input voltage	V _I = 5.5 V				100	μΑ	
Iн	High-level input current	V _I = 2.7 V				50	μA	
۱ _L	Low-level input current	V ₁ = 0.5 V				-400	μA	
los	Short-circuit output current§	V _I = 2 V			-40	-140	mA	
	Supply surrent (all drivers)	Outputs disabled				105	m (
I _{CC} Supply current (all drivers)		Outputs enabled, No load				85	mA	

 $\Delta |V_{OD}|$ and $\Delta |V_{OC}|$ are the changes in magnitude of V_{OD} and V_{OC} , respectively, that occur when the input is changed from a high level to a low level.

[‡] In ANSI Standard TIA/EIA-422-B, V_{OC}, which is the average of the two output voltages with respect to ground, is called output offset voltage, VOS.

§ Only one output at a time should be shorted, and duration of the short circuit should not exceed one second.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V

PARAMETER		TEST CONDITIONS			MAX	UNIT	
^t PLH	Propagation delay time, low- to high-level output	Ci = 15 pE	Soo Figuro 2		20	20	
^t PHL	Propagation delay time, high- to low-level output	С[= 15 рг,	C _L = 15 pF, See Figure 2		20	ns	
t _{sk}	Skew time	C _L = 15 pF,	See Figure 2		6	ns	
^t t(OD)	Differential-output transition time	C _L = 15 pF,	See Figure 3		20	ns	
^t PZH	Output enable time to high level				30		
t _{PZL}	Output enable time to low level	C _L = 50 pF,	50 pF, See Figure 4		30	ns	
^t PHZ	Output disable time from high level	C. 50 pF	See Figure 4		25		
^t PLZ	Output disable time from low level	C _L = 50 pF, See Figure 4			30	ns	



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PARAMETER MEASUREMENT INFORMATION

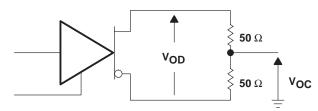
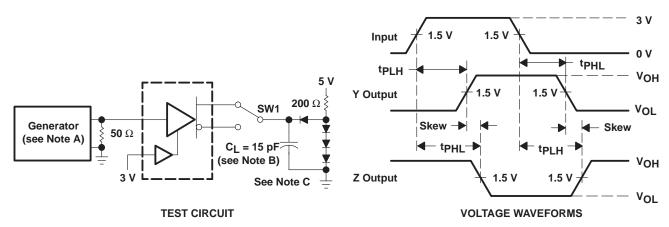


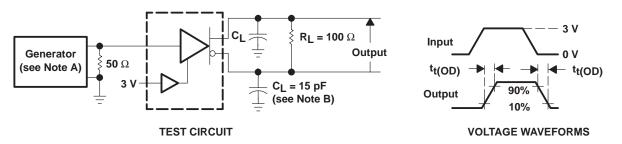
Figure 1. Differential and Common-Mode Output Voltages



NOTES: A. The input pulse is supplied by a generator having the following characteristics: $t_f \le 5$ ns, $t_f \le 5$ ns, PRR ≤ 1 MHz, duty cycle = 50%, $Z_O = 50 \Omega$.

- B. $\tilde{C_L}$ includes probe and stray capacitance.
- C. All diodes are 1N916 or 1N3064.

Figure 2. Test Circuit and Voltage Waveforms

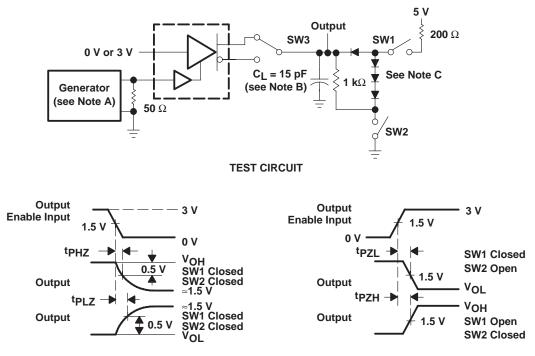


- NOTES: A. The input pulse is supplied by a generator having the following characteristics: $t_f \le 5$ ns, $t_f \le 5$ ns, PRR ≤ 1 MHz, duty cycle = 50%, $Z_O = 50 \Omega$.
 - B. CL includes probe and stray capacitance.

Figure 3. Test Circuit and Voltage Waveforms



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PARAMETER MEASUREMENT INFORMATION

VOLTAGE WAVEFORMS

- NOTES: A. The input pulse is supplied by a generator having the following characteristics: $t_f \le 5$ ns, $t_f \le 5$ ns, PRR ≤ 1 MHz, duty cycle = 50%, $Z_O = 50 \Omega$.
 - B. CL includes probe and stray capacitance.
 - C. All diodes are 1N916 or 1N3064.

Figure 4. Driver Test Circuit and Voltage Waveforms



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
MC3487D	ACTIVE	SOIC	D	16	40	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
MC3487DR	ACTIVE	SOIC	D	16	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
MC3487J	OBSOLETE	CDIP	J	16		None	Call TI	Call TI
MC3487N	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
MC3487NSR	ACTIVE	SO	NS	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

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J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012 variation AC.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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